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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1664
Number of Logic Elements/Cells	16640
Total RAM Bits	212992
Number of I/O	488
Number of Gates	1052000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k400efc672-3n

Email: info@E-XFL.COM

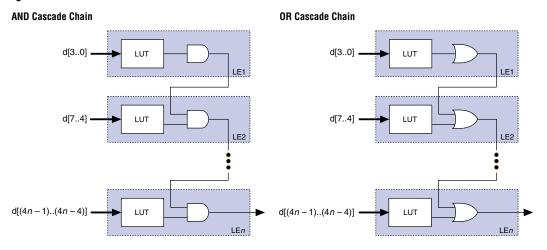
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Cascade Chain

With the cascade chain, the APEX 20K architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry.

Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. Figure 7 shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.

Figure 7. APEX 20K Cascade Chain



LE Operating Modes

The APEX 20K LE can operate in one of the following three modes:

- Normal mode
- Arithmetic mode
- Counter mode

Each mode uses LE resources differently. In each mode, seven available inputs to the LE—the four data inputs from the LAB local interconnect, the feedback from the programmable register, and the carry-in and cascade-in from the previous LE—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear, asynchronous preset, asynchronous load, synchronous clear, synchronous load, and clock enable control for the register. These LAB-wide signals are available in all LE modes.

The Quartus II software, in conjunction with parameterized functions such as LPM and DesignWare functions, automatically chooses the appropriate mode for common functions such as counters, adders, and multipliers. If required, the designer can also create special-purpose functions that specify which LE operating mode to use for optimal performance. Figure 8 shows the LE operating modes.

Input/Output Clock Mode

The input/output clock mode contains two clocks. One clock controls all registers for inputs into the ESB: data input, WE, RE, read address, and write address. The other clock controls the ESB data output registers. The ESB also supports clock enable and asynchronous clear signals; these signals also control the reading and writing of registers independently. Input/output clock mode is commonly used for applications where the reads and writes occur at the same system frequency, but require different clock enable signals for the input and output registers. Figure 21 shows the ESB in input/output clock mode.

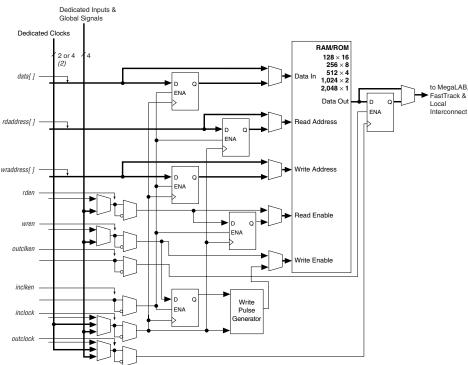


Figure 21. ESB in Input/Output Clock Mode Note (1)

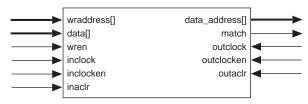
Notes to Figure 21:

- (1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

Single-Port Mode

The APEX 20K ESB also supports a single-port mode, which is used when simultaneous reads and writes are not required. See Figure 22.

Figure 23. APEX 20KE CAM Block Diagram



CAM can be used in any application requiring high-speed searches, such as networking, communications, data compression, and cache management.

The APEX 20KE on-chip CAM provides faster system performance than traditional discrete CAM. Integrating CAM and logic into the APEX 20KE device eliminates off-chip and on-chip delays, improving system performance.

When in CAM mode, the ESB implements 32-word, 32-bit CAM. Wider or deeper CAM can be implemented by combining multiple CAMs with some ancillary logic implemented in LEs. The Quartus II software combines ESBs and LEs automatically to create larger CAMs.

CAM supports writing "don't care" bits into words of the memory. The "don't-care" bit can be used as a mask for CAM comparisons; any bit set to "don't-care" has no effect on matches.

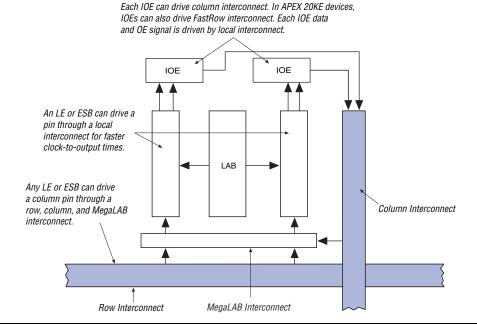
The output of the CAM can be encoded or unencoded. When encoded, the ESB outputs an encoded address of the data's location. For instance, if the data is located in address 12, the ESB output is 12. When unencoded, the ESB uses its 16 outputs to show the location of the data over two clock cycles. In this case, if the data is located in address 12, the 12th output line goes high. When using unencoded outputs, two clock cycles are required to read the output because a 16-bit output bus is used to show the status of 32 words.

The encoded output is better suited for designs that ensure duplicate data is not written into the CAM. If duplicate data is written into two locations, the CAM's output will be incorrect. If the CAM may contain duplicate data, the unencoded output is a better solution; CAM with unencoded outputs can distinguish multiple data locations.

CAM can be pre-loaded with data during configuration, or it can be written during system operation. In most cases, two clock cycles are required to write each word into CAM. When "don't-care" bits are used, a third clock cycle is required.

Figure 28 shows how a column IOE connects to the interconnect.

Figure 28. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KE devices incorporate an enhancement to support bidirectional pins with high internal fanout such as PCI control signals. These pins are called Dedicated Fast I/O pins (FAST1, FAST2, FAST3, and FAST4) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fanout logic signal distribution. They also can drive out. The Dedicated Fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Table 15. APEX 20K ClockLock & ClockBoost Parameters for -1 Speed-Grade Devices (Part 2 of 2)						
Symbol	Parameter	Min	Max	Unit		
t _{SKEW}	Skew delay between related ClockLock/ClockBoost-generated clocks		500	ps		
t _{JITTER}	Jitter on ClockLock/ClockBoost-generated clock (5)		200	ps		
t _{INCLKSTB}	Input clock stability (measured between adjacent clocks)		50	ps		

Notes to Table 15:

- (1) The PLL input frequency range for the EP20K100-1X device for 1x multiplication is 25 MHz to 175 MHz.
- (2) All input clock specifications must be met. The PLL may not lock onto an incoming clock if the clock specifications are not met, creating an erroneous clock within the device.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured first. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration, because the lock time is less than the configuration time.
- (4) The jitter specification is measured under long-term observation.
- (5) If the input clock stability is 100 ps, t_{JITTER} is 250 ps.

Table 16 summarizes the APEX 20K ClockLock and ClockBoost parameters for -2 speed grade devices.

Symbol	Parameter	Min	Min Max		
f _{OUT}	Output frequency	25	170	MHz	
f _{CLK1}	Input clock frequency (ClockBoost clock multiplication factor equals 1)	25	170	MHz	
f _{CLK2}	Input clock frequency (ClockBoost clock multiplication factor equals 2)	16	80	MHz	
f _{CLK4}	Input clock frequency (ClockBoost clock multiplication factor equals 4)	10	34	MHz	
t _{OUTDUTY}	Duty cycle for ClockLock/ClockBoost-generated clock	40	60	%	
f _{CLKDEV}	Input deviation from user specification in the Quartus II software (ClockBoost clock multiplication factor equals one) (1)		25,000 (2)	PPM	
t _R	Input rise time		5	ns	
t _F	Input fall time		5	ns	
t _{LOCK}	Time required for ClockLock/ ClockBoost to acquire lock (3)		10	μѕ	
t _{SKEW}	Skew delay between related ClockLock/ ClockBoost-generated clock	500	500	ps	
t _{JITTER}	Jitter on ClockLock/ ClockBoost-generated clock (4)		200	ps	
t _{INCLKSTB}	Input clock stability (measured between adjacent clocks)		50	ps	

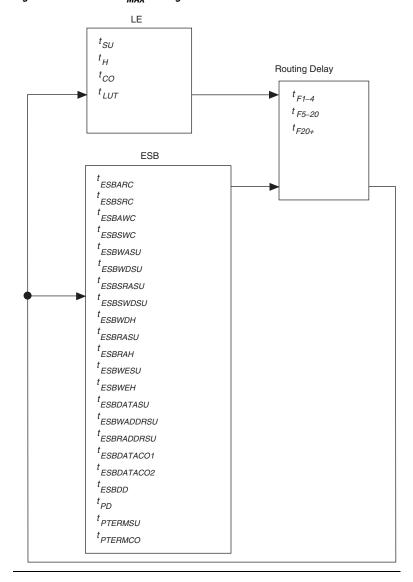


Figure 37. APEX 20KE f_{MAX} Timing Model

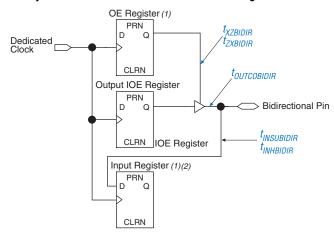


Figure 40. Synchronous Bidirectional Pin External Timing

Notes to Figure 40:

- (1) The output enable and input registers are LE registers in the LAB adjacent to a bidirectional row pin. The output enable register is set with "Output Enable Routing= Signal-Pin" option in the Quartus II software.
- (2) The LAB adjacent input register is set with "Decrease Input Delay to Internal Cells=Off". This maintains a zero hold time for lab adjacent registers while giving a fast, position independent setup time. A faster setup time with zero hold time is possible by setting "Decrease Input Delay to Internal Cells=ON" and moving the input register farther away from the bidirectional pin. The exact position where zero hold occurs with the minimum setup time, varies with device density and speed grade.

Table 31 describes the f_{MAX} timing parameters shown in Figure 36 on page 68.

Symbol	Parameter					
t _{SU}	LE register setup time before clock					
t _H	LE register hold time after clock					
t_{CO}	LE register clock-to-output delay					
t _{LUT}	LUT delay for data-in					
t _{ESBRC}	ESB Asynchronous read cycle time					
t _{ESBWC}	ESB Asynchronous write cycle time					
t _{ESBWESU}	ESB WE setup time before clock when using input register					
t _{ESBDATASU}	ESB data setup time before clock when using input register					
t _{ESBDATAH}	ESB data hold time after clock when using input register					
t _{ESBADDRSU}	ESB address setup time before clock when using input registers					
t _{ESBDATACO1}	ESB clock-to-output delay when using output registers					

Table 36. APEX 20KE Routing Timing Microparameters Note (1)						
Symbol	Parameter					
t _{F1-4}	-anout delay using Local Interconnect					
t _{F5-20}	Fanout delay estimate using MegaLab Interconnect					
t _{F20+}	Fanout delay estimate using FastTrack Interconnect					

Note to Table 36:

(1) These parameters are worst-case values for typical applications. Post-compilation timing simulation and timing analysis are required to determine actual worst-case performance.

Table 37. APE	Table 37. APEX 20KE Functional Timing Microparameters					
Symbol	Parameter					
TCH	Minimum clock high time from clock pin					
TCL	Minimum clock low time from clock pin					
TCLRP	LE clear Pulse Width					
TPREP	LE preset pulse width					
TESBCH	Clock high time for ESB					
TESBCL	Clock low time for ESB					
TESBWP	Write pulse width					
TESBRP	Read pulse width					

Tables 38 and 39 describe the APEX 20KE external timing parameters.

Table 38. APEX 20KE External Timing Parameters Note (1)					
Symbol	Conditions				
t _{INSU}	Setup time with global clock at IOE input register				
t _{INH}	Hold time with global clock at IOE input register				
t _{OUTCO}	Clock-to-output delay with global clock at IOE output register	C1 = 10 pF			
t _{INSUPLL}	Setup time with PLL clock at IOE input register				
t _{INHPLL}	Hold time with PLL clock at IOE input register				
t _{OUTCOPLL}	Clock-to-output delay with PLL clock at IOE output register	C1 = 10 pF			

Symbol	Parameter	Conditions
t _{INSUBIDIR}	Setup time for bidirectional pins with global clock at LAB adjacent Input Register	
t _{INHBIDIR}	Hold time for bidirectional pins with global clock at LAB adjacent Input Register	
^t OUTCOBIDIR	Clock-to-output delay for bidirectional pins with global clock at IOE output register	C1 = 10 pF
t _{XZBIDIR}	Synchronous Output Enable Register to output buffer disable delay	C1 = 10 pF
t _{ZXBIDIR}	Synchronous Output Enable Register output buffer enable delay	C1 = 10 pF
t _{INSUBIDIRPLL}	Setup time for bidirectional pins with PLL clock at LAB adjacent Input Register	
t _{INHBIDIRPLL}	Hold time for bidirectional pins with PLL clock at LAB adjacent Input Register	
[†] OUTCOBIDIRPLL	Clock-to-output delay for bidirectional pins with PLL clock at IOE output register	C1 = 10 pF
t _{XZBIDIRPLL}	Synchronous Output Enable Register to output buffer disable delay with PLL	C1 = 10 pF
t _{ZXBIDIRPLL}	Synchronous Output Enable Register output buffer enable delay with PLL	C1 = 10 pF

Note to Tables 38 and 39:

⁽¹⁾ These timing parameters are sample-tested only.

Symbol	-1 Spee	d Grade	-2 Spee	d Grade	-3 Speed Grade		Units
	Min	Max	Min	Max	Min	Max	
t _{SU}	0.5		0.6		0.8		ns
t _H	0.7		0.8		1.0		ns
t _{CO}		0.3		0.4		0.5	ns
t _{LUT}		0.8		1.0		1.3	ns
t _{ESBRC}		1.7		2.1		2.4	ns
t _{ESBWC}		5.7		6.9		8.1	ns
t _{ESBWESU}	3.3		3.9		4.6		ns
t _{ESBDATASU}	2.2		2.7		3.1		ns
t _{ESBDATAH}	0.6		0.8		0.9		ns
t _{ESBADDRSU}	2.4		2.9		3.3		ns
t _{ESBDATACO1}		1.3		1.6		1.8	ns
t _{ESBDATACO2}		2.6		3.1		3.6	ns
t _{ESBDD}		2.5		3.3		3.6	ns
t _{PD}		2.5		3.0		3.6	ns
t _{PTERMSU}	2.3		2.7		3.2		ns
t _{PTERMCO}		1.5		1.8		2.1	ns
t _{F1-4}		0.5		0.6		0.7	ns
t _{F5-20}		1.6		1.7		1.8	ns
t _{F20+}		2.2		2.2		2.3	ns
t _{CH}	2.0		2.5		3.0		ns
t_{CL}	2.0		2.5		3.0		ns
t _{CLRP}	0.3		0.4		0.4		ns
t _{PREP}	0.4		0.5		0.5		ns
t _{ESBCH}	2.0		2.5		3.0		ns
t _{ESBCL}	2.0		2.5		3.0		ns
t _{ESBWP}	1.6		1.9		2.2		ns
t _{ESBRP}	1.0		1.3	_	1.4		ns

Notes to Tables 43 through 48:

- (1) This parameter is measured without using ClockLock or ClockBoost circuits.
- (2) This parameter is measured using ClockLock or ClockBoost circuits.

Tables 49 through 54 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K30E APEX 20KE devices.

Table 49. EP20K30E f _{MAX} LE Timing Microparameters									
Symbol	_	1	-	2	-;	3	Unit		
	Min	Max	Min	Max	Min	Max			
t _{SU}	0.01		0.02		0.02		ns		
t _H	0.11		0.16		0.23		ns		
t _{CO}		0.32		0.45		0.67	ns		
t _{LUT}		0.85		1.20		1.77	ns		

Table 69. EP20K160E f _{MAX} Routing Delays										
Symbol	-	1		-2		3	Unit			
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.25		0.26		0.28	ns			
t _{F5-20}		1.00		1.18		1.35	ns			
t _{F20+}		1.95		2.19		2.30	ns			

Symbol	-1		-	-2 -3		3	Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.34		1.43		1.55		ns
t _{CL}	1.34		1.43		1.55		ns
t _{CLRP}	0.18		0.19		0.21		ns
t _{PREP}	0.18		0.19		0.21		ns
t _{ESBCH}	1.34		1.43		1.55		ns
t _{ESBCL}	1.34		1.43		1.55		ns
t _{ESBWP}	1.15		1.45		1.73		ns
t _{ESBRP}	0.93		1.15		1.38		ns

Symbol	-	1	-	2	-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.23		2.34		2.47		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	5.07	2.00	5.59	2.00	6.13	ns
t _{INSUPLL}	2.12		2.07		=		ns
t _{INHPLL}	0.00		0.00		=		ns
toutcople	0.50	3.00	0.50	3.35	-	-	ns

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.68		2.06		2.24	ns
t _{ESBSRC}		2.27		2.77		3.18	ns
t _{ESBAWC}		3.10		3.86		4.50	ns
t _{ESBSWC}		2.90		3.67		4.21	ns
t _{ESBWASU}	0.55		0.67		0.74		ns
t _{ESBWAH}	0.36		0.46		0.48		ns
t _{ESBWDSU}	0.69		0.83		0.95		ns
t _{ESBWDH}	0.36		0.46		0.48		ns
t _{ESBRASU}	1.61		1.90		2.09		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.42		1.71		2.01		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.06		-0.07		0.05		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.13		0.31		ns
t _{ESBRADDRSU}	0.18		0.23		0.39		ns
t _{ESBDATACO1}		1.09		1.35		1.51	ns
t _{ESBDATACO2}		2.19		2.75		3.22	ns
t _{ESBDD}		2.75		3.41		4.03	ns
t _{PD}		1.58		1.97		2.33	ns
t _{PTERMSU}	1.00		1.22		1.51		ns
t _{PTERMCO}		1.10		1.37		1.09	ns

Table 75. EP2	0K200E f _{MAX} 1	Routing Delay	s				
Symbol	-	1		-2	-:	Unit	
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.25		0.27		0.29	ns
t _{F5-20}		1.02		1.20		1.41	ns
t _{F20+}		1.99		2.23		2.53	ns

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.79		2.44		3.25	ns
t _{ESBSRC}		2.40		3.12		4.01	ns
t _{ESBAWC}		3.41		4.65		6.20	ns
t _{ESBSWC}		3.68		4.68		5.93	ns
t _{ESBWASU}	1.55		2.12		2.83		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.71		2.33		3.11		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.72		2.34		3.13		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.63		2.36		3.28		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.07		0.39		0.80		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.27		0.67		1.17		ns
t _{ESBRADDRSU}	0.34		0.75		1.28		ns
t _{ESBDATACO1}		1.03		1.20		1.40	ns
t _{ESBDATACO2}		2.33		3.18		4.24	ns
t _{ESBDD}		3.41		4.65		6.20	ns
t _{PD}		1.68		2.29		3.06	ns
t _{PTERMSU}	0.96		1.48		2.14		ns
t _{PTERMCO}		1.05		1.22		1.42	ns

Table 81. EP2	OK300E f _{MAX} I	Routing Delay	s				
Symbol	-	1		2	-	3	Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.22		0.24		0.26	ns
t _{F5-20}		1.33		1.43		1.58	ns
t _{F20+}		3.63		3.93		4.35	ns

Table 92. EP20K	600E f _{MAX} ESE	3 Timing Micr	oparameters				
Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	d Grade	Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.67		2.39		3.11	ns
t _{ESBSRC}		2.27		3.07		3.86	ns
t _{ESBAWC}		3.19		4.56		5.93	ns
t _{ESBSWC}		3.51		4.62		5.72	ns
t _{ESBWASU}	1.46		2.08		2.70		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.60		2.29		2.97		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.61		2.30		2.99		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.49		2.30		3.11		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.01		0.35		0.71		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.19		0.62		1.06		ns
t _{ESBRADDRSU}	0.25		0.71		1.17		ns
t _{ESBDATACO1}		1.01		1.19		1.37	ns
t _{ESBDATACO2}		2.18		3.12		4.05	ns
t _{ESBDD}		3.19		4.56		5.93	ns
t _{PD}		1.57		2.25		2.92	ns
t _{PTERMSU}	0.85		1.43		2.01		ns
t _{PTERMCO}		1.03		1.21		1.39	ns

Table 93. EP20K600E f _{MAX} Routing Delays										
Symbol	-1 Spee	d Grade	-2 Spe	ed Grade	-3 Spee	Unit				
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.22		0.25		0.26	ns			
t _{F5-20}		1.26		1.39		1.52	ns			
t _{F20+}		3.51		3.88		4.26	ns			

Symbol	-1 Spee	d Grade	-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.78		2.02		1.95	ns
t _{ESBSRC}		2.52		2.91		3.14	ns
t _{ESBAWC}		3.52		4.11		4.40	ns
t _{ESBSWC}		3.23		3.84		4.16	ns
t _{ESBWASU}	0.62		0.67		0.61		ns
t _{ESBWAH}	0.41		0.55		0.55		ns
t _{ESBWDSU}	0.77		0.79		0.81		ns
t _{ESBWDH}	0.41		0.55		0.55		ns
t _{ESBRASU}	1.74		1.92		1.85		ns
t _{ESBRAH}	0.00		0.01		0.23		ns
t _{ESBWESU}	2.07		2.28		2.41		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.25		0.27		0.29		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.04		0.11		ns
t _{ESBRADDRSU}	0.14		0.11		0.16		ns
t _{ESBDATACO1}		1.29		1.50		1.63	ns
t _{ESBDATACO2}		2.55		2.99		3.22	ns
t _{ESBDD}		3.12		3.57		3.85	ns
t _{PD}		1.84		2.13		2.32	ns
t _{PTERMSU}	1.08		1.19		1.32	_	ns
t _{PTERMCO}		1.31		1.53		1.66	ns

Table 105. EP20K1500E f _{MAX} Routing Delays										
Symbol	-1 Spee	d Grade	-2 Spe	ed Grade	-3 Spee	Unit				
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.28		0.28		0.28	ns			
t _{F5-20}		1.36		1.50		1.62	ns			
t _{F20+}		4.43		4.48		5.07	ns			

Table 110. Selectable I/O Standard Output Delays									
Symbol	-1 Spec	-1 Speed Grade		ed Grade	-3 Spee	d Grade	Unit		
	Min	Max	Min	Max	Min	Max	Min		
LVCMOS		0.00		0.00		0.00	ns		
LVTTL		0.00		0.00		0.00	ns		
2.5 V		0.00		0.09		0.10	ns		
1.8 V		2.49		2.98		3.03	ns		
PCI		-0.03		0.17		0.16	ns		
GTL+		0.75		0.75		0.76	ns		
SSTL-3 Class I		1.39		1.51		1.50	ns		
SSTL-3 Class II		1.11		1.23		1.23	ns		
SSTL-2 Class I		1.35		1.48		1.47	ns		
SSTL-2 Class II		1.00		1.12		1.12	ns		
LVDS		-0.48		-0.48		-0.48	ns		
CTT		0.00		0.00		0.00	ns		
AGP		0.00		0.00		0.00	ns		

Power Consumption

To estimate device power consumption, use the interactive power calculator on the Altera web site at http://www.altera.com.

Configuration & Operation

The APEX 20K architecture supports several configuration schemes. This section summarizes the device operating modes and available device configuration schemes.

Operating Modes

The APEX architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called *command mode*; normal device operation is called *user mode*.

Before and during device configuration, all I/O pins are pulled to $V_{\mbox{\scriptsize CCIO}}$ by a built-in weak pull-up resistor.

Version 4.1

APEX 20K Programmable Logic Device Family Data Sheet version 4.1 contains the following changes:

- t_{ESBWEH} added to Figure 37 and Tables 35, 50, 56, 62, 68, 74, 86, 92, 97, and 104.
- Updated EP20K300E device internal and external timing numbers in Tables 79 through 84.



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